



Material Content Data Sheet



Sales Product Name				IAUS300N04S4N007		Issued		31. July 2018	
MA#				MA002634530					
Package				PG-HSOG-8-1		Weight*		704.78 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	7.727	1.10	1.10	10964	10964	
leadframe	inorganic material	phosphorus	7723-14-0	0.040	0.01		57		
	non noble metal	iron	7439-89-6	0.134	0.02		191		
	non noble metal	copper	7440-50-8	134.219	19.04	19.07	190440	190688	
	non noble metal	aluminium	7429-90-5	14.176	2.01	2.01	20114	20114	
wire	non noble metal	aluminium	7429-90-5	14.176	2.01	2.01	20114	20114	
encapsulation	organic material	carbon black	1333-86-4	3.865	0.55		5483		
	plastics	epoxy resin	-	42.510	6.03		60317		
	inorganic material	silicondioxide	60676-86-0	211.264	29.98	36.56	299757	365557	
leadfinish	non noble metal	tin	7440-31-5	8.309	1.18	1.18	11790	11790	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.220	0.03	0.03	311	312	
solder	non noble metal	tin	7440-31-5	0.125	0.02		177		
	noble metal	silver	7440-22-4	0.156	0.02		222		
	non noble metal	lead	7439-92-1	5.973	0.85	0.89	8475	8874	
heatspreader	inorganic material	phosphorus	7723-14-0	0.083	0.01		118		
	non noble metal	iron	7439-89-6	0.276	0.04		392		
	non noble metal	copper	7440-50-8	275.705	39.11	39.16	391191	391701	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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